

# NTMFS4983NF

## Power MOSFET

30 V, 106 A, Single N-Channel, SO-8 FL

### Features

- Integrated Schottky Diode
- Low  $R_{DS(on)}$  to Minimize Conduction Losses
- Low Capacitance to Minimize Driver Losses
- Optimized Gate Charge to Minimize Switching Losses
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

### Applications

- CPU Power Delivery
- Synchronous Rectification for DC-DC Converters
- Low Side Switching
- Telecom Secondary Side Rectification

**MAXIMUM RATINGS** ( $T_J = 25^\circ\text{C}$  unless otherwise stated)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V <sub>DSS</sub>	30	V
Gate-to-Source Voltage			V <sub>GS</sub>	±20	V
Continuous Drain Current R <sub>θJA</sub> (Note 1)	Steady State	T <sub>A</sub> = 25°C	I <sub>D</sub>	30	A
		T <sub>A</sub> = 85°C		22	
Power Dissipation R <sub>θJA</sub> (Note 1)		T <sub>A</sub> = 25°C	P <sub>D</sub>	3.13	W
Continuous Drain Current R <sub>θJA</sub> ≤ 10 sec		T <sub>A</sub> = 25°C	I <sub>D</sub>	48	A
		T <sub>A</sub> = 85°C		34	
Power Dissipation R <sub>θJA</sub> , t ≤ 10 sec		T <sub>A</sub> = 25°C	P <sub>D</sub>	7.7	W
Continuous Drain Current R <sub>θJA</sub> (Note 2)		T <sub>A</sub> = 25°C	I <sub>D</sub>	22	A
		T <sub>A</sub> = 85°C		16	
Power Dissipation R <sub>θJA</sub> (Note 2)		T <sub>A</sub> = 25°C	P <sub>D</sub>	1.7	W
Continuous Drain Current R <sub>θJC</sub> (Note 1)		T <sub>C</sub> = 25°C	I <sub>D</sub>	106	A
		T <sub>C</sub> = 85°C		76	
Power Dissipation R <sub>θJC</sub> (Note 1)		T <sub>C</sub> = 25°C	P <sub>D</sub>	38	W
Pulsed Drain Current	t <sub>p</sub> =10μs	T <sub>A</sub> = 25°C	I <sub>DM</sub>	320	A
Current limited by package		T <sub>A</sub> = 25°C	I <sub>Dmaxpkg</sub>	100	A
Operating Junction and Storage Temperature			T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C
Source Current (Body Diode)			I <sub>S</sub>	54	A
Drain to Source dV/dt			dV/dt	6	V/ns
Single Pulse Drain-to-Source Avalanche Energy (V <sub>DD</sub> = 50 V, V <sub>GS</sub> = 10 V, I <sub>L</sub> = 45 A <sub>pk</sub> , L = 0.1 mH, R <sub>G</sub> = 25 Ω)			EAS	101	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			T <sub>L</sub>	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

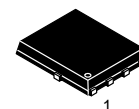
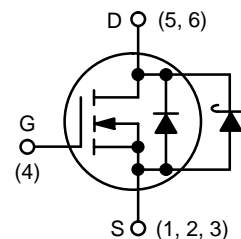


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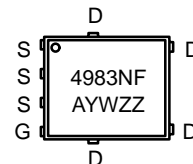
$V_{(BR)DSS}$	$R_{DS(ON)} \text{ MAX}$	$I_D \text{ MAX}$
30 V	2.1 m $\Omega$ @ 10 V	106 A
	3.1 m $\Omega$ @ 4.5 V	

### N-CHANNEL MOSFET



SO-8 FLAT LEAD  
CASE 488AA  
STYLE 1

### MARKING DIAGRAM



A = Assembly Location  
Y = Year  
W = Work Week  
ZZ = Lot Traceability

### ORDERING INFORMATION

Device	Package	Shipping†
NTMFS4983NFT1G	SO-8FL (Pb-Free)	1500 / Tape & Reel
NTMFS4983NFT3G	SO-8FL (Pb-Free)	5000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**THERMAL RESISTANCE MAXIMUM RATINGS**

Parameter	Symbol	Value	Unit
Junction-to-Case (Drain)	$R_{\theta JC}$	3.3	°C/W
Junction-to-Ambient – Steady State (Note 1)	$R_{\theta JA}$	40	
Junction-to-Ambient – Steady State (Note 2)	$R_{\theta JA}$	74	
Junction-to-Ambient – $t \leq 10$ sec	$R_{\theta JA}$	16.3	

1. Surface-mounted on FR4 board using 1 sq-in pad, 2 oz Cu.
2. Surface-mounted on FR4 board using the minimum recommended pad size of 100 mm<sup>2</sup>.

**ELECTRICAL CHARACTERISTICS** ( $T_J = 25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
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**OFF CHARACTERISTICS**

Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 1.0\text{ mA}$	30			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$V_{(BR)DSS}/T_J$	$I_D = 10\text{ mA}$ , referenced to $25^\circ\text{C}$		15		mV/°C
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{GS} = 0\text{ V}, V_{DS} = 24\text{ V}$ $T_J = 25^\circ\text{C}$			500	μA
Gate-to-Source Leakage Current	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$			±100	nA

**ON CHARACTERISTICS** (Note 3)

Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 1.0\text{ mA}$	1.2	1.7	2.3	V
Negative Threshold Temperature Coefficient	$V_{GS(TH)}/T_J$	$I_D = 10\text{ mA}$ , referenced to $25^\circ\text{C}$		5.0		mV/°C
Drain-to-Source On Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$ $I_D = 30\text{ A}$		1.6	2.1	mΩ
		$I_D = 15\text{ A}$		1.6		
		$V_{GS} = 4.5\text{ V}$ $I_D = 30\text{ A}$		2.5	3.1	
		$I_D = 15\text{ A}$		2.5		
Forward Transconductance	$g_{FS}$	$V_{DS} = 1.5\text{ V}, I_D = 15\text{ A}$		60		S

**CHARGES AND CAPACITANCES**

Input Capacitance	$C_{ISS}$	$V_{GS} = 0\text{ V}, f = 1\text{ MHz}, V_{DS} = 15\text{ V}$		3250		pF
Output Capacitance	$C_{OSS}$			1340		
Reverse Transfer Capacitance	$C_{RSS}$			90		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = 4.5\text{ V}, V_{DS} = 15\text{ V}; I_D = 30\text{ A}$		22.6		nC
Threshold Gate Charge	$Q_{G(TH)}$			2.9		
Gate-to-Source Charge	$Q_{GS}$			7.0		
Gate-to-Drain Charge	$Q_{GD}$			6.9		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = 10\text{ V}, V_{DS} = 15\text{ V}, I_D = 30\text{ A}$		47.9		nC

**SWITCHING CHARACTERISTICS** (Note 4)

Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = 4.5\text{ V}, V_{DS} = 15\text{ V}, I_D = 15\text{ A}, R_G = 3.0\text{ }\Omega$		13.5		ns
Rise Time	$t_r$			24.9		
Turn-Off Delay Time	$t_{d(OFF)}$			28.7		
Fall Time	$t_f$			10.7		

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .
4. Switching characteristics are independent of operating junction temperatures.

# NTMFS4983NF

## ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
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### SWITCHING CHARACTERISTICS (Note 4)

Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = 10\text{ V}, V_{DS} = 15\text{ V},$ $I_D = 15\text{ A}, R_G = 3.0\ \Omega$		9.4		ns
Rise Time	$t_r$			16.7		
Turn-Off Delay Time	$t_{d(OFF)}$			35.2		
Fall Time	$t_f$			7.4		

### DRAIN-SOURCE DIODE CHARACTERISTICS

Forward Diode Voltage	$V_{SD}$	$V_{GS} = 0\text{ V},$ $I_S = 2\text{ A}$	$T_J = 25^\circ\text{C}$		0.4	0.7	V
			$T_J = 125^\circ\text{C}$		0.32		
Reverse Recovery Time	$t_{RR}$	$V_{GS} = 0\text{ V}, dI_S/dt = 100\text{ A}/\mu\text{s},$ $I_S = 2\text{ A}$			45		ns
Charge Time	$t_a$				23		
Discharge Time	$t_b$				22		
Reverse Recovery Charge	$Q_{RR}$				50		nC

### PACKAGE PARASITIC VALUES

Source Inductance	$L_S$	$T_A = 25^\circ\text{C}$		0.65		nH
Drain Inductance	$L_D$			0.20		
Gate Inductance	$L_G$			1.5		
Gate Resistance	$R_G$			1.0		$\Omega$

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: pulse width  $\leq 300\ \mu\text{s}$ , duty cycle  $\leq 2\%$ .

4. Switching characteristics are independent of operating junction temperatures.

TYPICAL PERFORMANCE CURVES

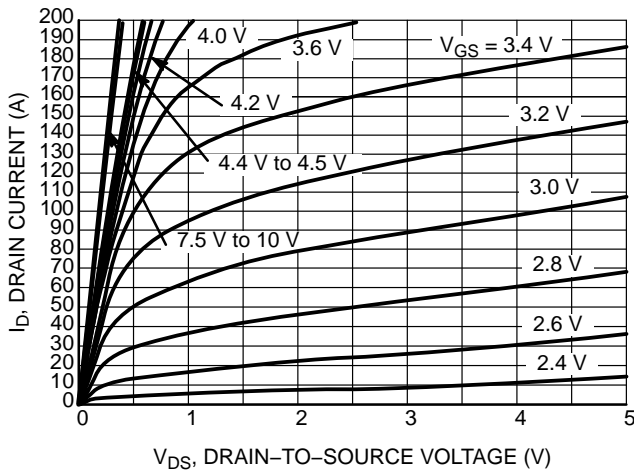


Figure 1. On-Region Characteristics

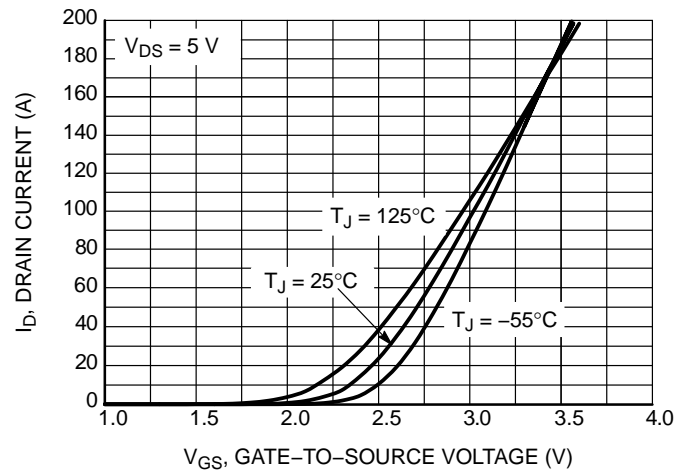


Figure 2. Transfer Characteristics

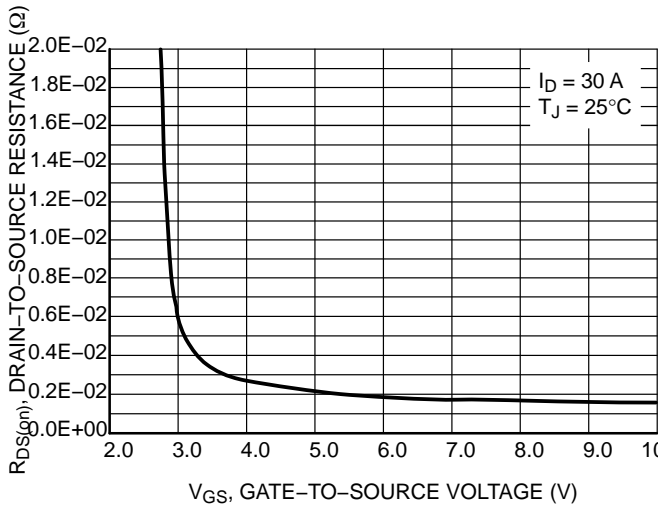


Figure 3. On-Resistance vs. Gate-to-Source Voltage

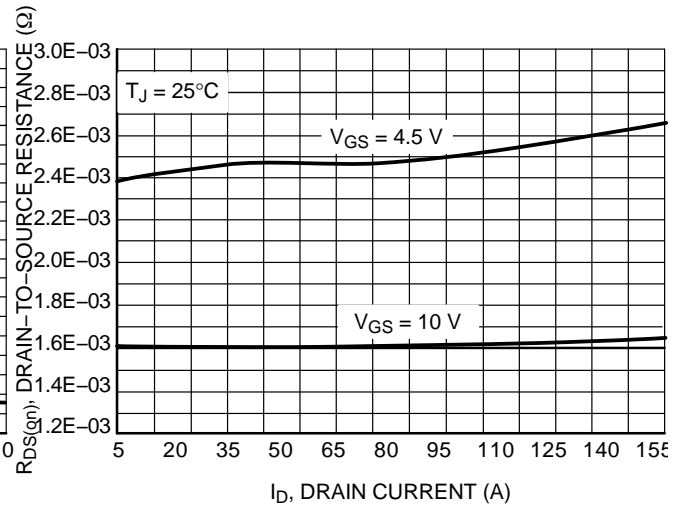


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

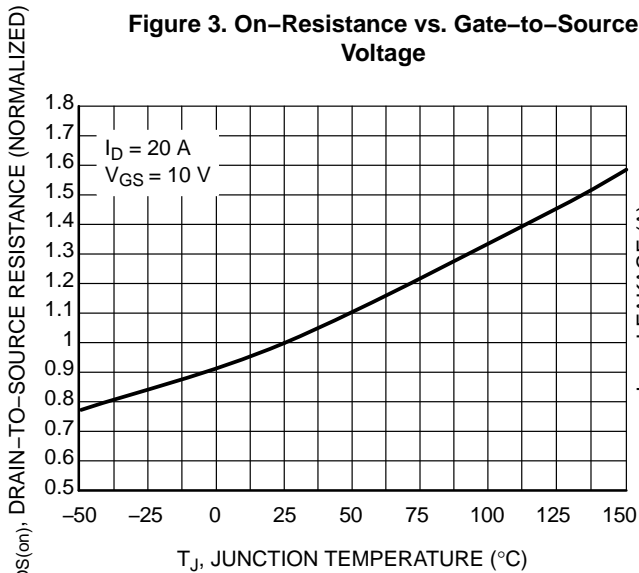


Figure 5. On-Resistance Variation with Temperature

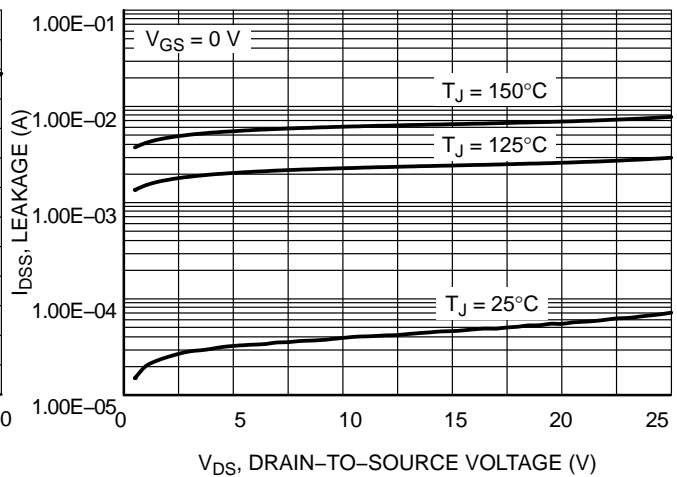


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL PERFORMANCE CURVES

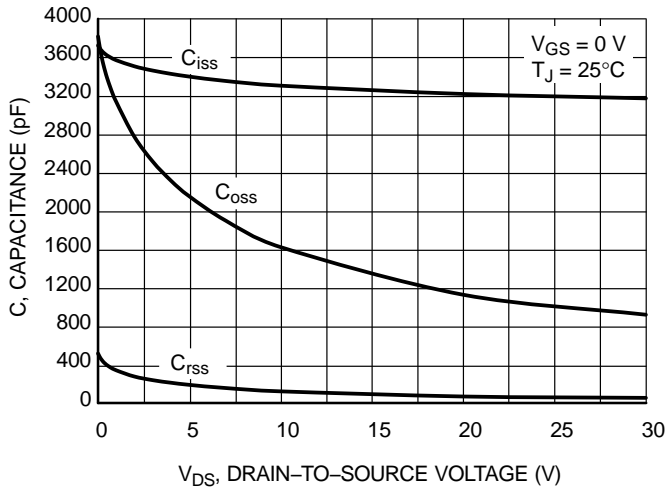


Figure 7. Capacitance Variation

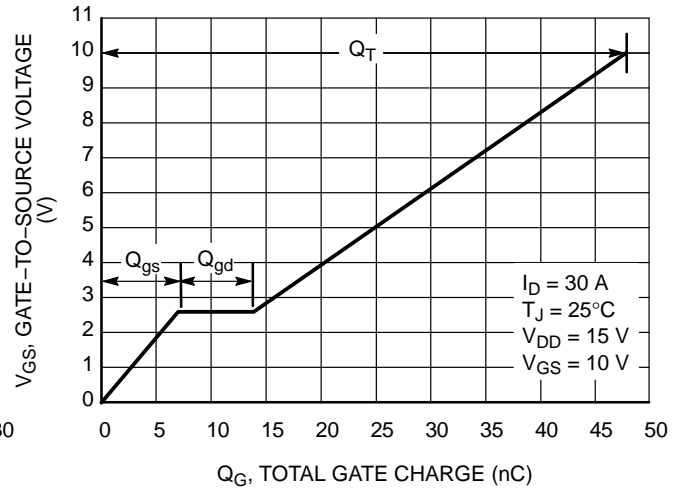


Figure 8. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

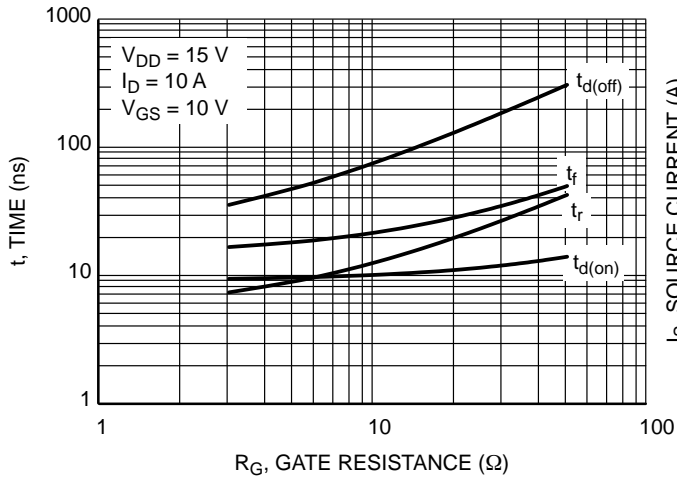


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

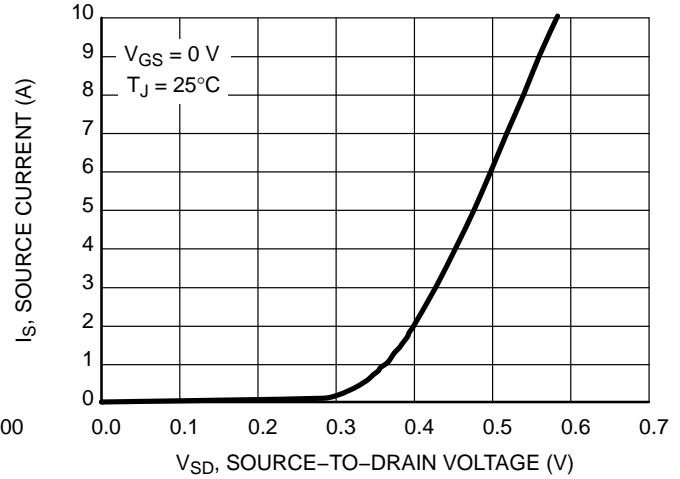


Figure 10. Diode Forward Voltage vs. Current

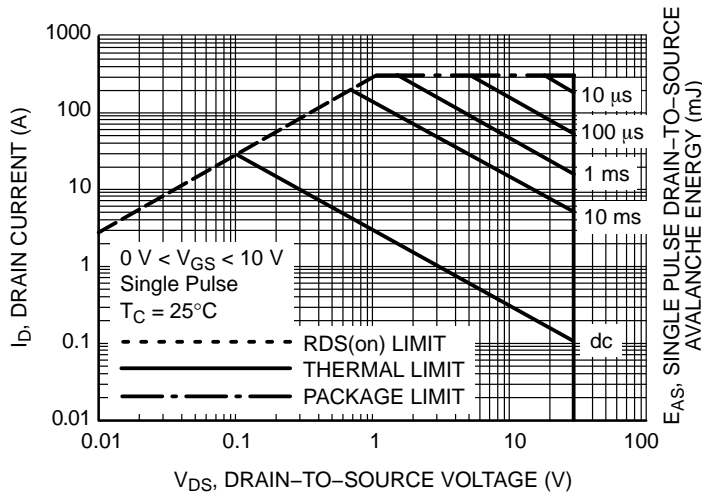


Figure 11. Maximum Rated Forward Biased Safe Operating Area

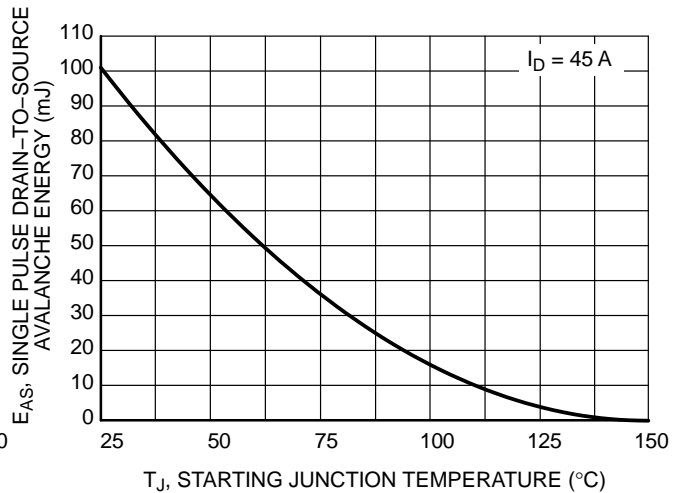


Figure 12. Maximum Avalanche Energy vs. Starting Junction Temperature

# NTMFS4983NF

## TYPICAL PERFORMANCE CURVES

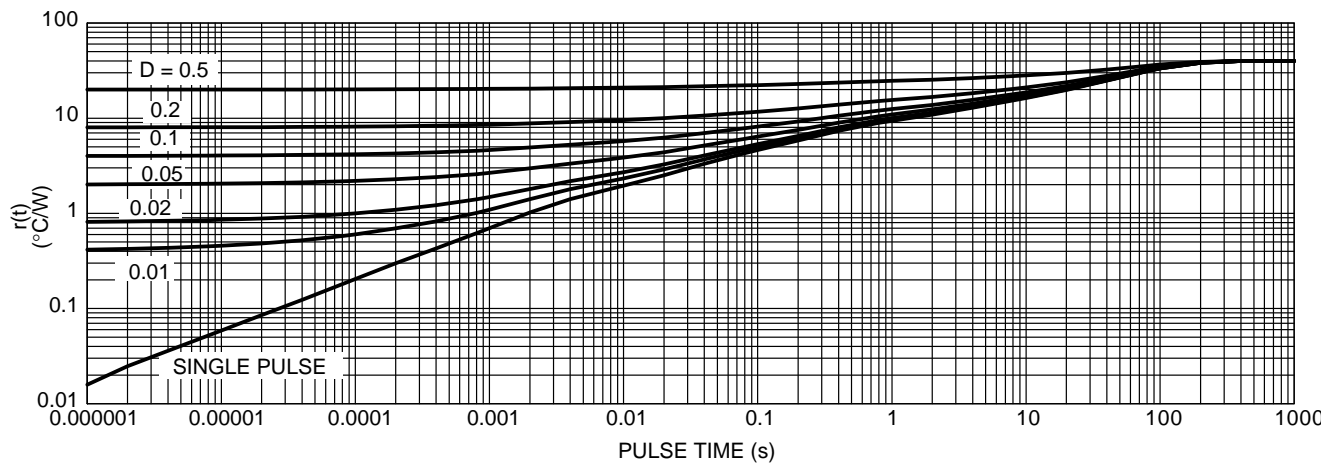


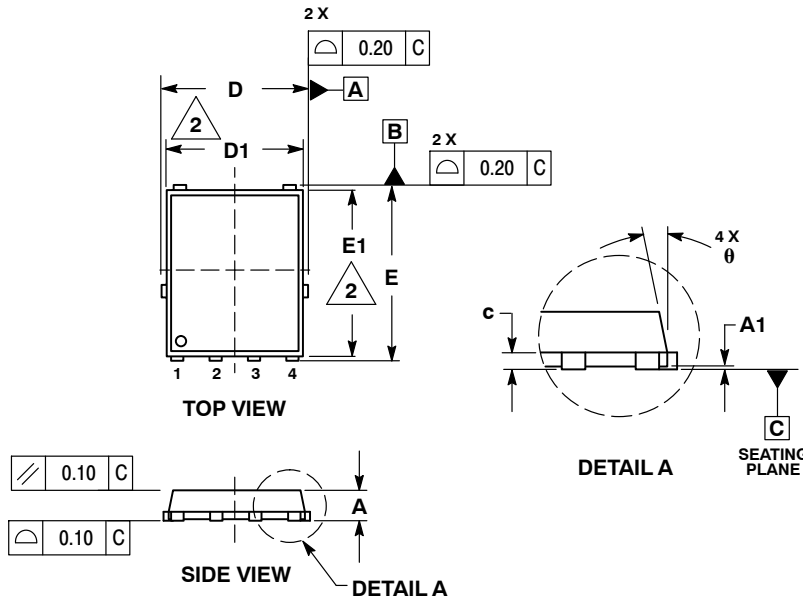
Figure 13. Thermal Response



SCALE 2:1

**DFN5 5x6, 1.27P**  
**(SO-8FL)**  
**CASE 488AA**  
**ISSUE N**

DATE 25 JUN 2018



## NOTES:

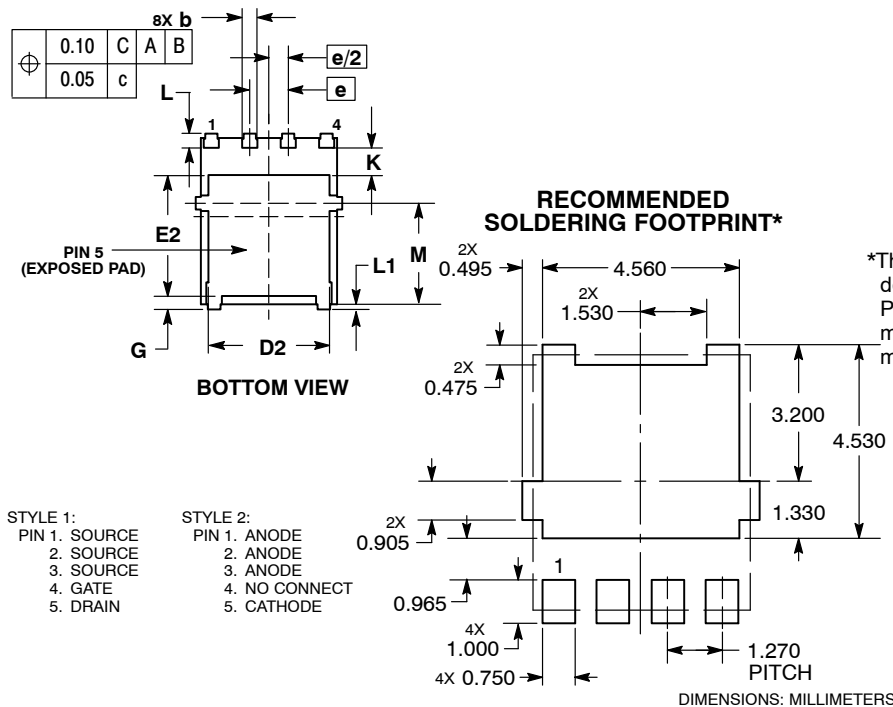
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.90	1.00	1.10
A1	0.00	---	0.05
b	0.33	0.41	0.51
c	0.23	0.28	0.33
D	5.00	5.15	5.30
D1	4.70	4.90	5.10
D2	3.80	4.00	4.20
E	6.00	6.15	6.30
E1	5.70	5.90	6.10
E2	3.45	3.65	3.85
e	1.27 BSC		
G	0.51	0.575	0.71
K	1.20	1.35	1.50
L	0.51	0.575	0.71
L1	0.125 REF		
M	3.00	3.40	3.80
θ	0°	---	12°

**GENERIC**  
**MARKING DIAGRAM\***


XXXXXX = Specific Device Code  
A = Assembly Location  
Y = Year  
W = Work Week  
ZZ = Lot Traceability

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.



\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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